

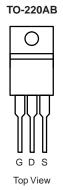
N-Channel 100-V (D-S) MOSFET

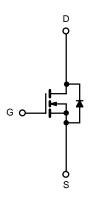
PRODUCT SUMMARY					
V _{DS} (V)	100				
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0. 036				
I _D (A) ^a	55				
Configuration	Single				

FEATURES

- TrenchFET® Power MOSFETS
- 175 °C Junction Temperature
- Low Thermal Resistance Package







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$r_{\rm C} = 25$ C, unless our	ei wise iiotea			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	I-	55		
	T _C = 125 °C	l _D	40		
Pulsed Drain Current		I _{DM}	135	A	
Avalanche Current		I _{AR}	35		
Repetitive Avalanche Energy ^a	L = 0.1 mH	E _{AR}	61	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	В	127 ^b	10/	
	T _A = 25 °C ^c	$ P_D$	3.75	W	
Operating Junction and Storage Temperature Range		T _I , T _{sta}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	(PCB Mount) ^c	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)		R _{thJC}	1.4	C/ V V		

Notes:

- a. Duty cycle ≤ 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{SS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 ,W _{GS} = 0 V			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V, T _J = 125 °C			50		
		$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 \text{ °C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	75			Α	
		$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.036		Ω	
	_	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$		0.038			
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C		0.050			
		V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C		0.065			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A	10			S	
Dynamic ^b	 						
Input Capacitance	C _{iss}			4500		pF	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		270			
Reverse Transfer Capacitance	C _{rss}			90			
Total Gate Charge ^c	Qg			35	60		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 40 \text{ A}$		11		nC	
Gate-Drain Charge ^c	Q _{gd}			9			
Gate Resistance	R _G			1.7		Ω	
Turn-On Delay Time ^c	t _{d(on)}			11	20		
Rise Time ^c	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 1.25 \Omega$		12	20		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 40 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$		30	45	ns	
Fall Time ^c	t _f			12	20	1	
Source-Drain Diode Ratings and Cha	racteristics T	_C = 25 °C ^b					
Continuous Current	Is				40		
Pulsed Current	I _{SM}				120	Α	
Forward Voltage ^a	V _{SD}	I _F = 30 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			60	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	$I_F = 30 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		5	8	Α	
Reverse Recovery Charge	Q _{rr}	·		0.15	0.4	иC	

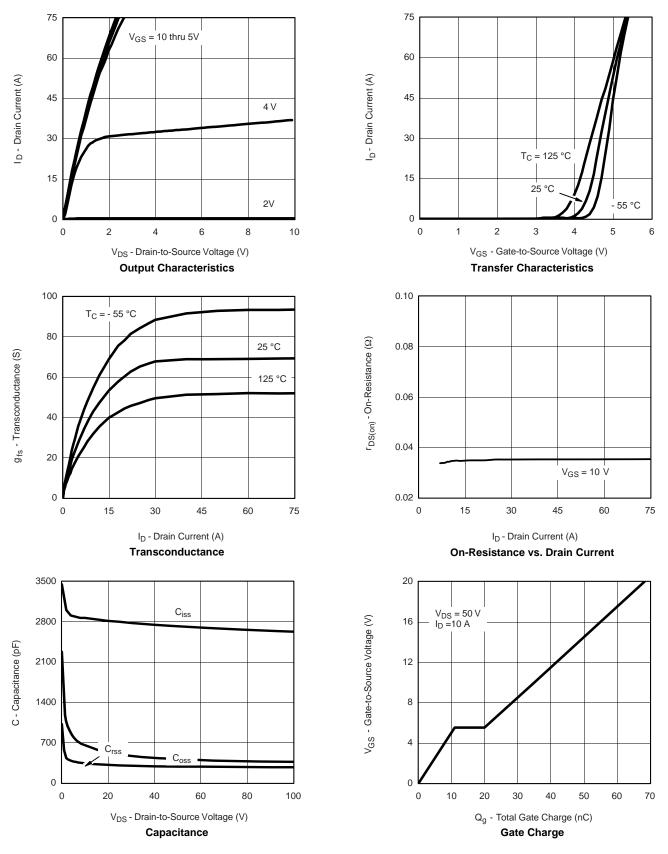
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

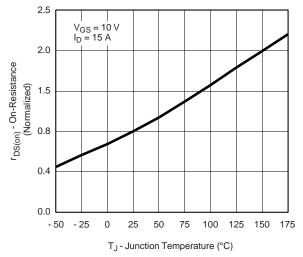


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

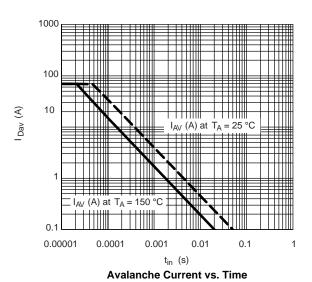




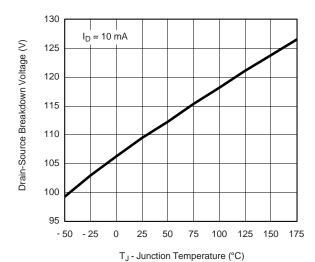
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On-Resistance vs. Junction Temperature



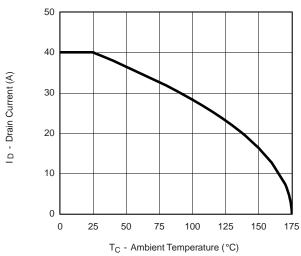
Source-Drain Diode Forward Voltage



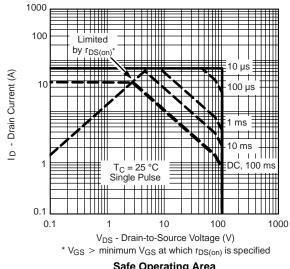
Drain-Source Breakdown Voltage vs. Junction Temperature



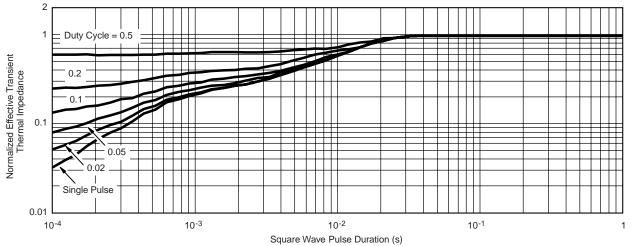
THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature



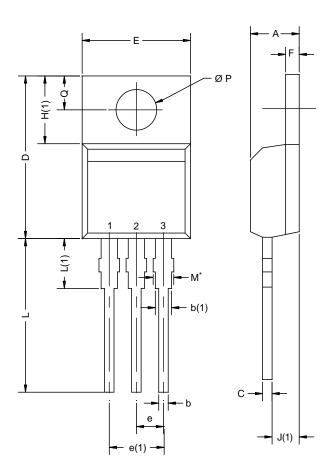




Normalized Thermal Transient Impedance, Junction-to-Case



TO-220AB



	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471					

Notes

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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